wherein a light emission portion for the plasma light is a slit-shaped gap formed along a lengthwise direction of a plate member.

2. (Amended) The laser oscillating apparatus according to claim 1, further comprising a shielding structure having a shielding wall covering said electromagnetic-wave emission source,

wherein said shielding structure is internally supplied with the laser gas, and wherein an upper surface of said shielding structure comprises said plate member.

3. (Amended) The laser oscillating apparatus according to claim 2, wherein said shielding structure comprises a pair of chambers communicating with each other via the gap.

4. (Amended) The laser oscillating apparatus according to claim 3, wherein an electromagnetic-wave emission source is provided in each of said chambers.

5. (Amended) The laser oscillating apparatus according to claim 1, wherein a waveguide comprising a pair of chambers internally supplied with laser gas is provided above and below said plate member, said pair of chambers in communication with each other via the gap,

and wherein an electromagnetic wave is generated in one of said pair of chambers and is propagated to the other one of said pair of chambers through the gap, to

continuously cause plasma light over the entire area along the lengthwise direction where the gap is formed.

6. (Amended) The laser oscillating apparatus according to claim 5, wherein an end of one of said pair of chambers is offset from the other one of said pair of chambers by a predetermined distance.

7. (Amended) The laser oscillating apparatus according to claim 21, wherein an opening of said electromagnetic-wave emission source is wider than the slit-shaped gap provided above the opening.

8. (Amended) A laser oscillating apparatus that excites a laser gas by an electromagnetic wave and resonates generated plasma light so as to generate laser light, comprising:

a waveguide comprising a pair of chambers each internally supplied with laser gas,

wherein said waveguide has a slit-shaped gap in a lengthwise direction, and said pair of chambers communicate with each other via the gap,

and wherein an electromagnetic wave is generated in one of said pair of chambers and is propagated to the other one of said pair of chambers through the gap, to continuously cause plasma light over the entire area along the lengthwise direction where the gap is formed.

9. (Amended) The laser oscillating apparatus according to claim 8, wherein an end of one of said pair of chambers is offset from the other one of said pair of chambers by a predetermined distance.

10. (Amended) The laser oscillating apparatus according to claim 1, wherein the laser gas is supplied in a flow direction orthogonal to a generation direction of laser light and across the gap.

11. (Amended) The laser oscillating apparatus according to claim 8, wherein the laser gas is supplied in a flow direction orthogonal to a generation direction of laser light and across the gap.

12. (Amended) The laser oscillating apparatus according to claim 1, wherein the electromagnetic wave is a microwave.

13. (Amended) The laser oscillating apparatus according to claim 8, wherein the electromagnetic wave is a microwave.

14. (Amended) The laser oscillating apparatus according to claim 1, wherein the laser gas is at least one inert gas selected from Kr, Ar, Ne and He or a gaseous mixture of the at least one inert gas and an F_2 gas.

15. (Amended) The laser oscillating apparatus according to claim 8, wherein the laser gas is at least one inert gas selected from Kr, Ar, Ne and He or a gaseous mixture of the at least one inert gas and an F_2 gas.

16. (Amended) An exposure apparatus comprising:

the laser oscillating apparatus according to claim 1, said laser oscillating apparatus being a light source that emits illumination light;

a first optical unit that irradiates a reticle, where a predetermined pattern is formed, with the illumination light from said laser oscillating apparatus; and

a second optical unit that irradiates an irradiated surface with the illumination light via said reticle,

wherein the predetermined pattern on said reticle is projected on the irradiated surface upon exposure of the irradiated surface.

17. (Amended) A device fabrication method comprising:

a step of applying a photosensitive material to an irradiated surface;

a step of exposing the irradiated surface coated with the photosensitive material via a predetermined pattern by using the exposure apparatus according to claim 16; and

a step of developing said photosensitive material exposed via the predetermined pattern.

18. (Amended) The device fabrication method according to claim 17, wherein the irradiated surface is a wafer surface, and wherein a semiconductor device is formed on the wafer surface.

19. (New) An exposure apparatus comprising:

the laser oscillating apparatus according to claim 8, said laser oscillating apparatus being a light source that emits illumination light;

a first optical unit that irradiates a reticle, where a predetermined pattern is formed, with the illumination light from said laser oscillating apparatus; and

a second optical unit that irradiates an irradiated surface with the illumination light via said reticle,

wherein the predetermined pattern on said reticle is projected on said irradiated surface upon exposure of the irradiated surface.

20. (New) A device fabrication method comprising:

a step of applying a photosensitive material to an irradiated surface;

a step of exposing the irradiated surface coated with the photosensitive material via a predetermined pattern by using the exposure apparatus according to claim 19; and

a step of developing the photosensitive material exposed via the predetermined pattern.

21. (New) The laser oscillating apparatus according to claim 1, wherein said plate member provided above and away from an electromagnetic-wave source.